DATA SHEET

NEC

MOS INTEGRATED CIRCUIT

μPD464318L, 464336L

4M-BIT Bi-CMOS SYNCHRONOUS FAST STATIC RAM
256K-WORD BY 18-BIT / 128K-WORD BY 36-BIT
HSTL INTERFACE

Description

The μPD464318L is a 262,144 words by 18 bits, and the μPD464336L is a 131,072 words by 36 bits synchronous static RAM fabricated with advanced Bi-CMOS technology using N-channel memory cell.

This technology and unique peripheral circuits make the μPD464318L and μPD464336L a high-speed device. The μPD464318L and μPD464336L are suitable for applications which require high-speed, low voltage, high-density memory and wide bit configuration, such as cache and buffer memory.

These are packaged in a 119-pin plastic BGA (Ball Grid Array).

Features

- Fully synchronous operation
- Fast clock access time : 2.6 ns / 200 MHz, 3.0 ns / 167 MHz, 3.5 ns / 154 MHz
- Single Differential Single clock, Registered Input / Registered Output
- Asynchronous output enable control : /G
- Byte write control : /SBa (DQa1-9), /SBb (DQb1-9), /SBc (DQc1-9), /SBd (DQd1-9)
- Common I/O using three-state outputs
- Internally self-timed write cycle
- Late write with 1 dead cycle between Read-Write
- User-configurable outputs :
  Controlled impedance outputs or push-pull outputs
- Boundary scan (JTAG) IEEE 1149.1 compatible
- 3.3 V (Chip) / 1.5V (I/O) supply

Ordering Information

Part number	Access time	Clock frequency	Package
μPD464318LS1-A5	2.6 ns	200 MHz	119-pin plastic BGA
μPD464318LS1-A6	3.0 ns	167 MHz	
μPD464318LS1-A65	3.5 ns	154 MHz	
μPD464336LS1-A5	2.6 ns	200 MHz	
μPD464336LS1-A6	3.0 ns	167 MHz	
μPD464336LS1-A65	3.5 ns	154 MHz	

The information in this document is subject to change without notice.

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Date Published September 1998 NS CP(K)
Printed in Japan

The mark ★ shows major revised points.

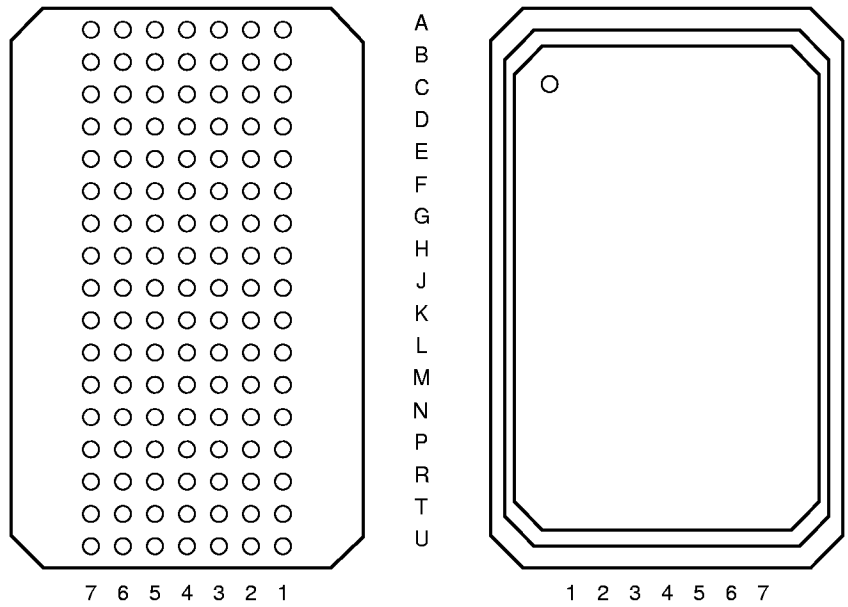
Pin Configurations

/xxx indicates active low signal.

119-pin Plastic BGA (256K Words by 18 Bits Pin Assignment)

[μPD464318LS1]

Bottom View **Top View**



	7		6		5		4		3		2		1	
	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.
A	A7	$V_{DD}Q$	A6	SA2	A5	SA6	A4	NC	A3	SA9	A2	SA12	A1	$V_{DD}Q$
B	B7	NC	B6	NC	B5	SA16	B4	NC	B3	SA17	B2	NC	B1	NC
C	C7	NC	C6	SA3	C5	SA7	C4	V_{DD}	C3	SA10	C2	SA13	C1	NC
D	D7	NC	D6	DQa9	D5	V_{SS}	D4	ZQ	D3	V_{SS}	D2	NC	D1	DQb1
E	E7	DQa8	E6	NC	E5	V_{SS}	E4	/SS	E3	V_{SS}	E2	DQb2	E1	NC
F	F7	$V_{DD}Q$	F6	DQa7	F5	V_{SS}	F4	/G	F3	V_{SS}	F2	NC	F1	$V_{DD}Q$
G	G7	DQa6	G6	NC	G5	V_{SS}	G4	NC	G3	/SBb	G2	DQb3	G1	NC
H	H7	NC	H6	DQa5	H5	V_{SS}	H4	NC	H3	V_{SS}	H2	NC	H1	DQb4
J	J7	$V_{DD}Q$	J6	V_{DD}	J5	V_{REF}	J4	V_{DD}	J3	V_{REF}	J2	V_{DD}	J1	$V_{DD}Q$
K	K7	DQa4	K6	NC	K5	V_{SS}	K4	K	K3	V_{SS}	K2	DQb5	K1	NC
L	L7	NC	L6	DQa3	L5	/SBa	L4	/K	L3	V_{SS}	L2	NC	L1	DQb6
M	M7	$V_{DD}Q$	M6	NC	M5	V_{SS}	M4	/SW	M3	V_{SS}	M2	DQb7	M1	$V_{DD}Q$
N	N7	NC	N6	DQa2	N5	V_{SS}	N4	SA1	N3	V_{SS}	N2	NC	N1	DQb8
P	P7	DQa1	P6	NC	P5	V_{SS}	P4	SA0	P3	V_{SS}	P2	DQb9	P1	NC
R	R7	NC	R6	SA4	R5	V_{DD}	R4	V_{DD}	R3	V_{SS}	R2	SA14	R1	NC
T	T7	NC	T6	SA5	T5	SA8	T4	NC	T3	SA11	T2	SA15	T1	NC
U	U7	$V_{DD}Q$	U6	NC	U5	TDO	U4	TCK	U3	TDI	U2	TMS	U1	$V_{DD}Q$

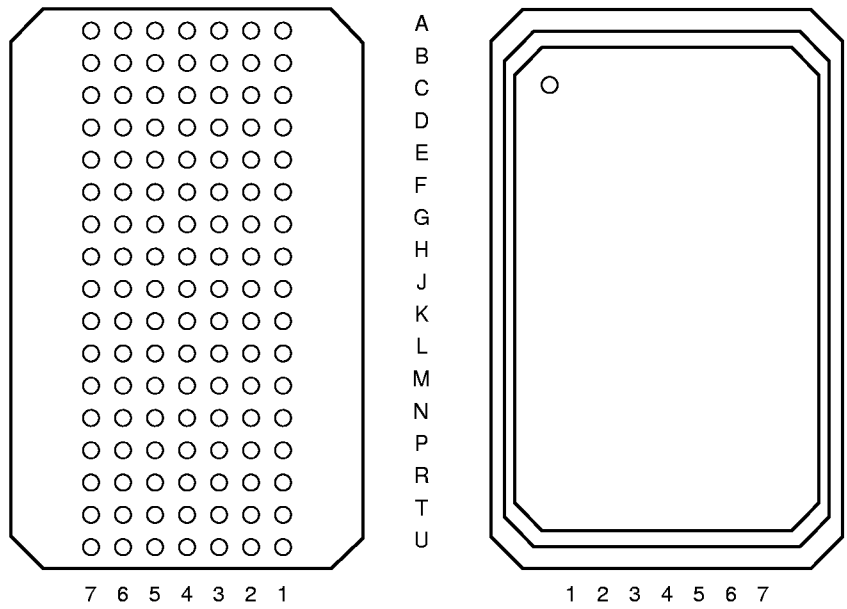
Pin Name and Functions

Pin name	Description	Function
V_{DD}	Core Power Supply	Supplies power for RAM core
V_{SS}	Ground	
$V_{DD}Q$	Output Power Supply	Supplies power for output buffers
V_{REF}	Input Reference	
K, /K	Main Clock Input	
SA0 to SA17	Synchronous Address Input	
DQa1 to DQb9	Synchronous Data Input / Output	
/SS	Synchronous Chip Select	Logically selects SRAM
/SW	Synchronous Byte Write Enable	
/SBa	Synchronous Byte "a" Write Enable	Write DQa1 to DQa9
/SBb	Synchronous Byte "b" Write Enable	Write DQb1 to DQb9
/G	Asynchronous Output Enable	Asynchronous input
ZQ	Output Impedance Control	
NC	No Connection	
TMS	Test Mode Select (JTAG)	
TDI	Test Data Input (JTAG)	
TCK	Test Clock Input (JTAG)	
TDO	Test Data Output (JTAG)	

119-pin plastic BGA (128K Words by 36 Bits Pin Assignment)

[μPD464336LS1]

Bottom View **Top View**



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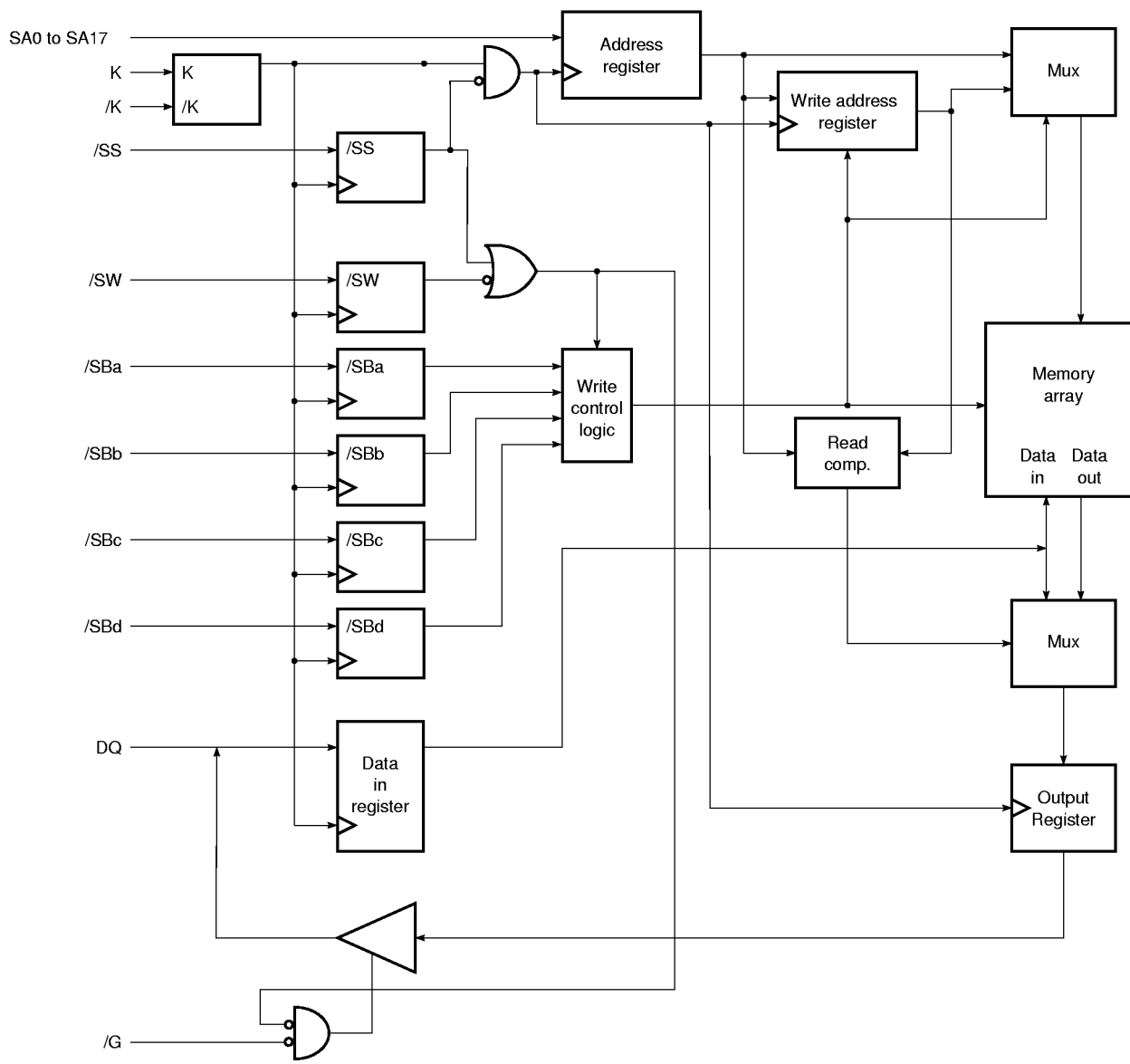
	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.	Pin No.	Func.
A	A7	V_{DDQ}	A6	SA2	A5	SA5	A4	NC	A3	SA9	A2	SA12	A1	V_{DDQ}
B	B7	NC	B6	NC	B5	SA15	B4	NC	B3	SA16	B2	NC	B1	NC
C	C7	NC	C6	SA3	C5	SA6	C4	V_{DD}	C3	SA10	C2	SA13	C1	NC
D	D7	DQb8	D6	DQb9	D5	V_{SS}	D4	ZQ	D3	V_{SS}	D2	DQc9	D1	DQc8
E	E7	DQb6	E6	DQb7	E5	V_{SS}	E4	/SS	E3	V_{SS}	E2	DQc7	E1	DQc6
F	F7	V_{DDQ}	F6	DQb5	F5	V_{SS}	F4	/G	F3	V_{SS}	F2	DQc5	F1	V_{DDQ}
G	G7	DQb3	G6	DQb4	G5	/SBb	G4	NC	G3	/SBc	G2	DQc4	G1	DQc3
H	H7	DQb1	H6	DQb2	H5	V_{SS}	H4	NC	H3	V_{SS}	H2	DQc2	H1	DQc1
J	J7	V_{DDQ}	J6	V_{DD}	J5	V_{REF}	J4	V_{DD}	J3	V_{REF}	J2	V_{DD}	J1	V_{DDQ}
K	K7	DQa1	K6	DQa2	K5	V_{SS}	K4	K	K3	V_{SS}	K2	DQd2	K1	DQd1
L	L7	DQa3	L6	DQa4	L5	/SBa	L4	/K	L3	/SBd	L2	DQd4	L1	DQd3
M	M7	V_{DDQ}	M6	DQa5	M5	V_{SS}	M4	/SW	M3	V_{SS}	M2	DQd5	M1	V_{DDQ}
N	N7	DQa6	N6	DQa7	N5	V_{SS}	N4	SA1	N3	V_{SS}	N2	DQd7	N1	DQd6
P	P7	DQa8	P6	DQa9	P5	V_{SS}	P4	SA0	P3	V_{SS}	P2	DQd9	P1	DQd8
R	R7	NC	R6	SA4	R5	V_{DD}	R4	V_{DD}	R3	V_{SS}	R2	SA14	R1	NC
T	T7	NC	T6	NC	T5	SA7	T4	SA8	T3	SA11	T2	NC	T1	NC
U	U7	V_{DDQ}	U6	NC	U5	TDO	U4	TCK	U3	TDI	U2	TMS	U1	V_{DDQ}

Pin Name and Functions

Pin name	Description	Function
V_{DD}	Core Power Supply	Supplies power for RAM core
V_{SS}	Ground	
$V_{DD}Q$	Output Power Supply	Supplies power for output buffers
V_{REF}	Input Reference	
K, /K	Main Clock	
SA0 to SA16	Synchronous Address Input	
DQa1 to DQd9	Synchronous Data Input / Output	
/SS	Synchronous Chip Select	Logically selects SRAM
/SW	Synchronous Byte Write Enable	
/SBa	Synchronous Byte "a" Write Enable	Write DQa1 to DQa9
/SBb	Synchronous Byte "b" Write Enable	Write DQb1 to DQb9
/SBc	Synchronous Byte "c" Write Enable	Write DQc1 to DQc9
/SBd	Synchronous Byte "d" Write Enable	Write DQd1 to DQd9
/G	Asynchronous Output Enable	Asynchronous input
ZQ	Output Impedance Control	
NC	No Connection	
TMS	Test Mode Select (JTAG)	
TDI	Test Data Input (JTAG)	
TCK	Test Clock Input (JTAG)	
TDO	Test Data Output (JTAG)	

★ Late Write Block Diagram



Synchronous Truth Table

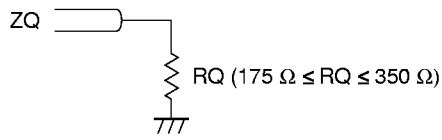
/SS	/SW	/SBa	/SBb	/SBc	/SBd	Mode	DQa1–9	DQb1–9	DQc1–9	DQd1–9	Power
H	×	×	×	×	×	Not selected	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Active
L	H	×	×	×	×	Read	Dout	Dout	Dout	Dout	Active
L	L	L	L	L	L	Write	Din	Din	Din	Din	Active
L	L	L	H	H	H	Write	Din	Hi-Z	Hi-Z	Hi-Z	Active
L	L	H	L	L	L	Write	Hi-Z	Din	Din	Din	Active

Remark × : Don't care

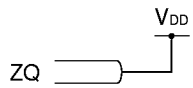
Mode Select (Output Buffer)

ZQ	Mode	Notes
IZQ × RQ	Controlled impedance push-pull output buffer mode	1
V_{DD}	Push-Pull output buffer mode	2

Notes 1. See figure.



2. See figure.



Electrical Specifications

Absolute Maximum Ratings

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit	Note
Supply voltage	V_{DD}		–0.5		+4	V	1
Output supply voltage	V_{DDQ}		–0.5		+4	V	1
Input voltage	V_{IN}		–0.5		V_{DD} + 0.3	V	1
Input / Output voltage	$V_{I/O}$		–0.5		V_{DDQ} + 0.3	V	1
Operating temperature	T_j		20		110	°C	2
Storage temperature	T_{stg}		–55		+125	°C	

Notes 1. –0.5 V MIN. (Pulse width 10% Tcyc)

2. T_j = Junction temperature

Caution Exposing the device to stress above those listed in Absolute Maximum Rating could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended DC Operating Conditions (T_j = 20 to 110 °C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Core supply voltage	V_{DD}		3.15	3.3	3.45	V
Output buffer supply voltage	V_{DDQ}		1.4	1.5	1.6	V
Input reference voltage	V_{REF}		0.6	0.95	1.3	V
Low level input voltage	V_{IL}		–0.3 Note		V_{REF}–0.1	V
High level input voltage	V_{IH}		V_{REF}+0.1		V_{DDQ}+0.3	V

Note –0.5 V MIN. (Pulse width 10% Tcyc)

Recommended AC Operating Conditions (T_j = 20 to 110 °C) Note

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input reference voltage	$V_{REF\ (RMS)}$		–5%		+5%	V
Low level input voltage	V_{IL}		–0.3		V_{REF}–0.2	V
High level input voltage	V_{IH}		V_{REF}+0.2		V_{DDQ}+0.3	V

Note T_j = 20 to 110°C : μPD464318L-A6/ -A65, 464336L-A6/ -A65

T_j = 20 to 100°C : μPD464318L-A5, 464336L-A5

Capacitance (T_A = 25 °C, f = 1 MHz)

Parameter Note	Symbol	Test conditions	MAX.	Unit
Input capacitance	C_{IN}	V_{IN} = 0 V	5	pF
Input / Output capacitance	$C_{I/O}$	$V_{I/O}$ = 0 V	7	pF
Clock pin (K, /K) input capacitance	C_{CLK}	V_{CLK} = 0 V	7	pF

Note These parameters are sampled and not 100% tested.

DC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)

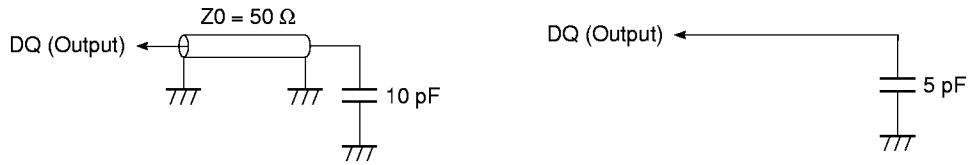
Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input leakage current	I_{LI}	V_{IN} = 0 to V_{DD}		–5		+5	μA
DQ leakage current Note	I_{LO}	$V_{I/O}$ = 0 to V_{DDQ}		–5		+5	μA
Operating supply current	I_{CC}	/SS = V_{IL}, IDQ = 0 mA	μPD464318L			600	mA
		200 MHz	μPD464336L			700	

Note /SS = V_{IH} or /G = V_{IH}

Output Voltage on Controlled Impedance Push-Pull Output Buffer Mode (VZQ = IZQ × RQ)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Low level output voltage	V_{OL}	| I_{OL} | ≤ 10 μA, I_{OL} = 2.5V_{DDQ} / RQ ± 10% V_{OL} = VDDQ / 2 (175 Ω < RQ < 350 Ω)	V_{SS}		0.1	V
High level output voltage	V_{OH}	| I_{OH} | ≤ 10 μA, I_{OH} = 2.5V_{DDQ} / RQ ± 10% V_{OH} = VDDQ / 2 (175 Ω < RQ < 350 Ω)	V_{DDQ}–0.1		V_{DDQ}	V

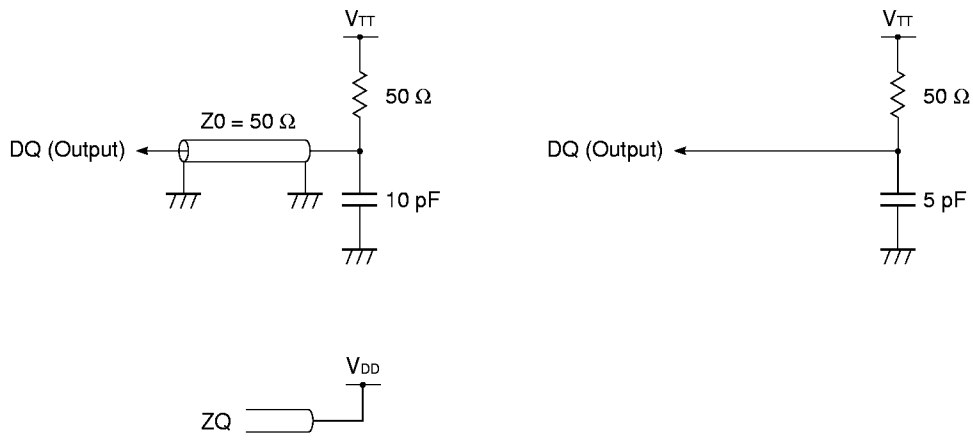
Remark See figure.



Output Voltage on Push-Pull Output Buffer Mode (VZQ = V_{DD})

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Low level output voltage	V_{OL}	I_{OL} = +4 mA	–		0.3	V
High level output voltage	V_{OH}	I_{OH} = –4 mA	V_{DDQ}–0.3		–	V

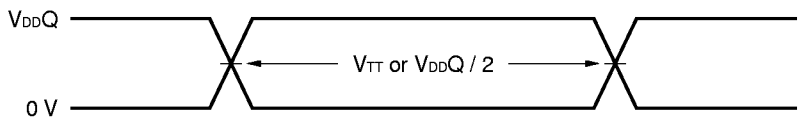
Remark See figure (V_{TT} = 0.75 V).



AC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)

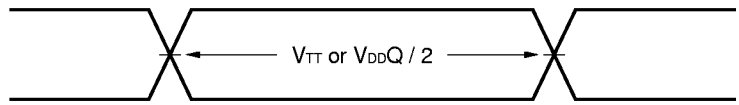
AC Characteristics Test Conditions

Input waveform (rise and fall time = 0.5 ns (20 to 80%))



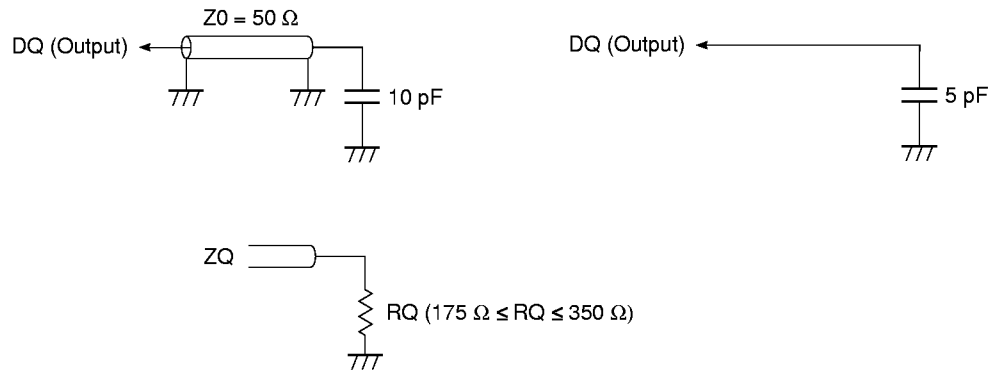
★ **Remark** Clock input differential voltage

Output waveform

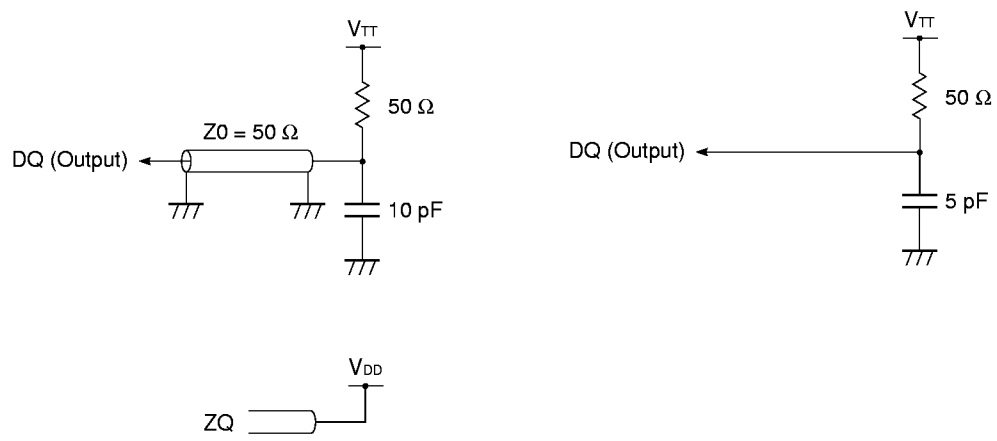


Output load

(1) Controlled impedance push-pull output buffer mode



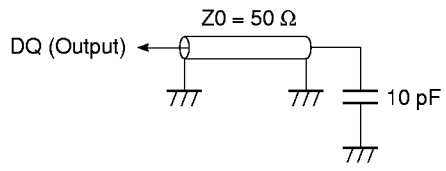
(2) Push-Pull output buffer mode (V_{TT}=0.75 V)

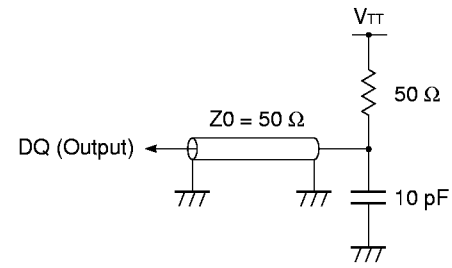


Single Differential Clock, Registered Input / Registered Output Mode

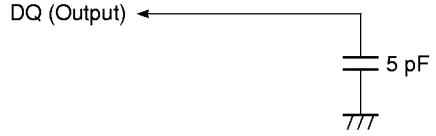
Parameter		Symbol	–A5 (200 MHz)		–A6 (167 MHz)		–A65 (154 MHz)		Unit	Notes
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Clock cycle time		TKHKH	5.0	–	6.0	–	6.5	–	ns	
Clock phase time		TKHKL / TKLKH	2.4	–	2.5	–	3.0	–	ns	
Setup times	Address	TAVKH	0.5	–	0.5	–	0.5	–	ns	
	Write data	TDVKH								
	Write enable	TWVKH								
	Chip select	TSVKH								
Hold times	Address	TKHAX	1.0	–	1.0	–	1.0	–	ns	
	Write data	TKHDX								
	Write enable	TKHWX								
	Chip select	TKHSX								
Clock access time		TKHQV	–	2.6	–	3.0	–	3.5	ns	1
K high to Q change		TKHQX	1.0	–	1.0	–	1.0	–	ns	2
/G low to Q valid		TGLQV	–	2.5	–	3.0	–	3.5	ns	1
/G low to Q change		TGLQX	1.0	–	1.0	–	1.0	–	ns	2
/G high to Q Hi-Z		TGHQZ	1.0	2.5	1.0	3.0	1.0	3.5	ns	2
K high to Q Hi-Z (/SW)		TKHQZ	1.0	3.5	1.0	3.5	1.0	4.0	ns	2
K high to Q Hi-Z (/SS)		TKHQZ2	1.0	3.5	1.0	3.5	1.0	4.0	ns	2
K high to Q Lo-Z		TKHQX2	1.0	–	1.0	–	1.0	–	ns	
/G high Pulse width		TGHGL	5.0	–	6.0	–	6.5	–	ns	3
/G high to K high		TGHKH	1.0	–	1.0	–	1.0	–	ns	3
K high to /G low		TKHGL	2.5	–	2.5	–	2.5	–	ns	3

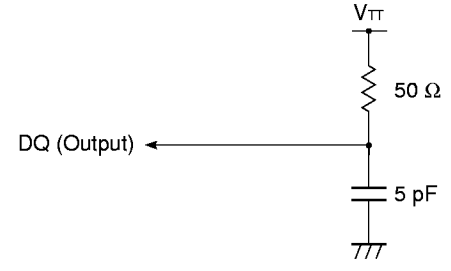
Notes 1. See figure.





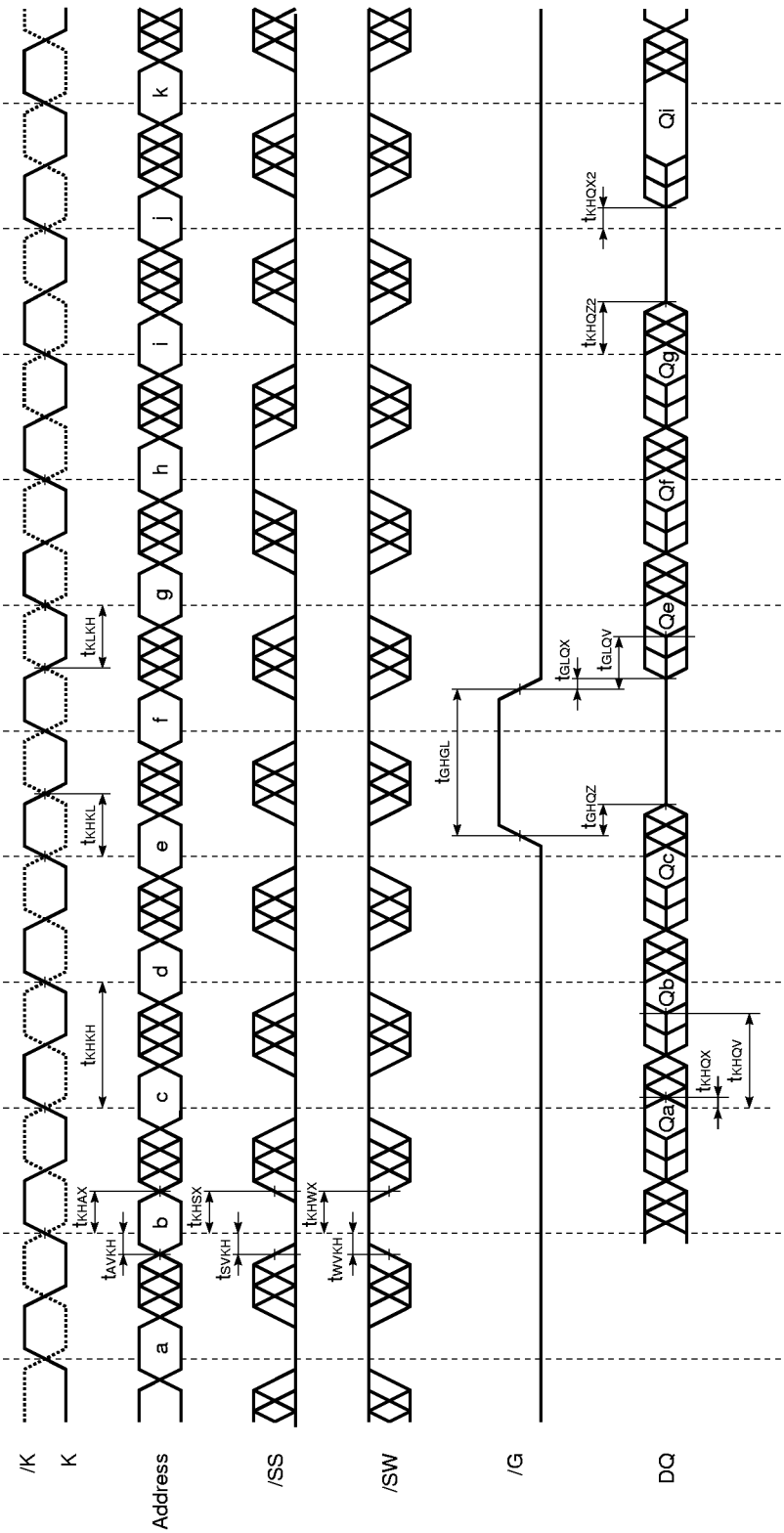
2. See figure.



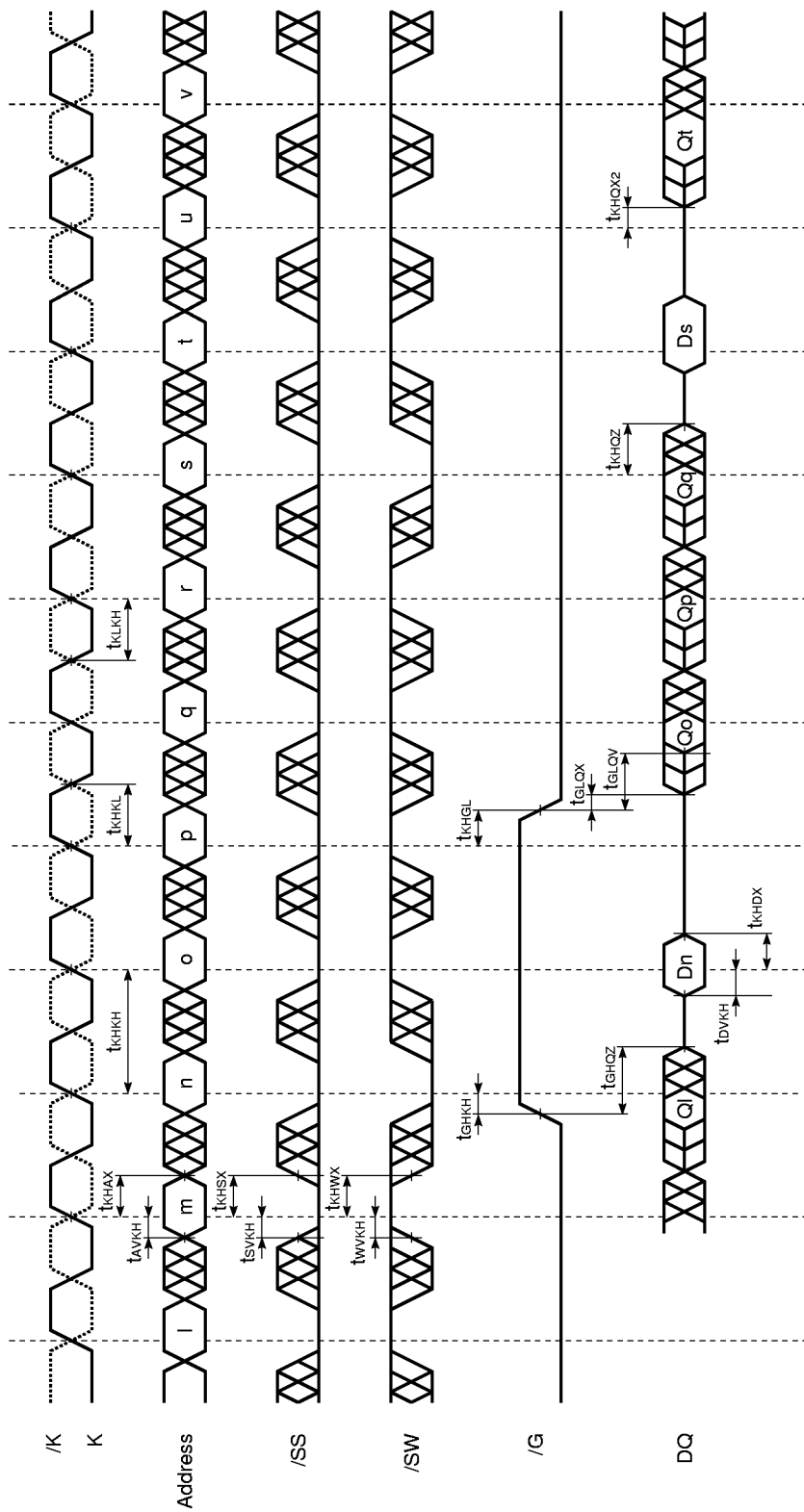


3. Controlled impedance push-pull output buffer mode only.

Single Differential Clock, Registered Input / Registered Output Mode (Read Operation)



Single Differential Clock, Registered Input / Registered Output Mode (Write Operation)



JTAG Specifications

The μPD464318L and μPD464336L support a limited set of JTAG functions as in IEEE standard 1149.1.

Test Access Port (TAP) Pins

Pin Name	Description	Pin Assignments
TCK	Test Clock Input	4 U
TMS	Test Mode Select	2 U
TDI	Test Data Input	3 U
TDO	Test Data Output	5 U

Remark The device does not have TRST (TAP reset). The TAP controller state is reset into TEST-LOGIC-RESET on the SRAM POWER-UP.

JTAG DC Characteristics (Tj = 20 to 110 °C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	Notes
JTAG input high voltage	V_{IH}		2.2		V_{DD}+0.3	V	
JTAG input low voltage	V_{IL}		–0.3		+0.8	V	
JTAG output high voltage	V_{OH}		2.4		–	V	1
JTAG output low voltage	V_{OL}		–		0.4	V	2

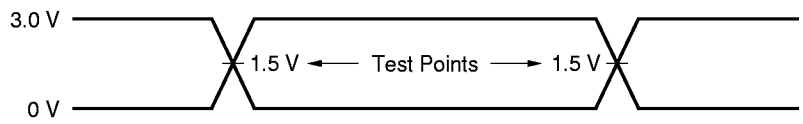
Notes 1. I_{OH} = –8 mA
2. I_{OL} = 8 mA

JTAG AC Characteristics (Tj = 20 to 110 °C)

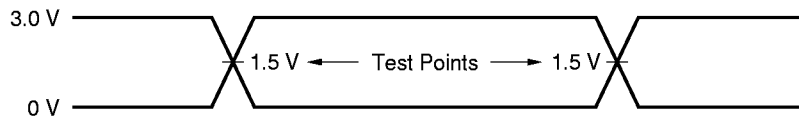
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	Note
Clock Cycle Time (TCK)	t_{THTH}		100		–	ns	
Clock Phase Time (TCK)	t_{THTL} / t_{TLTH}		40		–	ns	
Setup Time (TMS / TDI)	t_{MVTH} / t_{DVTH}		10		–	ns	
Hold Time (TMS / TDI)	t_{THMX} / t_{THDX}		10		–	ns	
TCK Low to TDO Valid (TDO)	t_{TLQV}		–		20	ns	

JTAG AC Test Conditions (Tj = 20 to 110 °C)

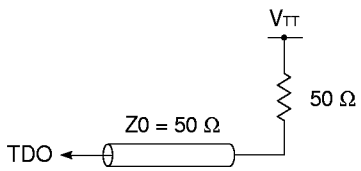
Input waveform (rise / fall time = 1 ns (20 to 50 %))



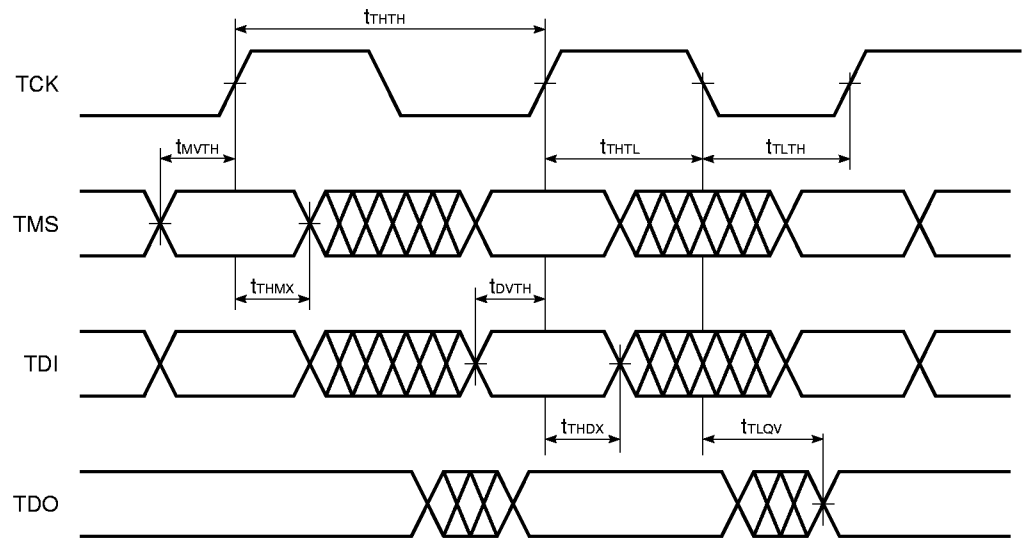
Output waveform



Output load (V_{TT}=1.5 V)



JTAG Timing Diagram



Scan Register Definition

Register name	256K x 18	128K x 36	Unit
Instruction register	3	3	bit
Bypass register	1	1	bit
ID register	32	32	bit
Boundary register	51	70	bit

ID Register Definition

Organization	ID [31:28] vendor revision no.	ID [27:12] part no.	ID [11:1] vendor ID no.	ID [0] fix bit
256K x 18	XXXX	0111001011 000000	00010010000	1
128K x 36	XXXX	0110101100 000000	00010010000	1

JTAG Instruction Cording

IR2	IR1	IR0	Instruction	Note
0	0	0	EXTEST	1
0	0	1	IDCODE	
0	1	0	SAMPLE-Z	1
0	1	1	BYPASS	
1	0	0	SAMPLE	
1	0	1	BYPASS	
1	1	0	BYPASS	
1	1	1	BYPASS	

Note 1. TRISTATE all data drivers and CAPTURE the pad values into a SERIAL SCAN LATCH.

SCAN Exit Order

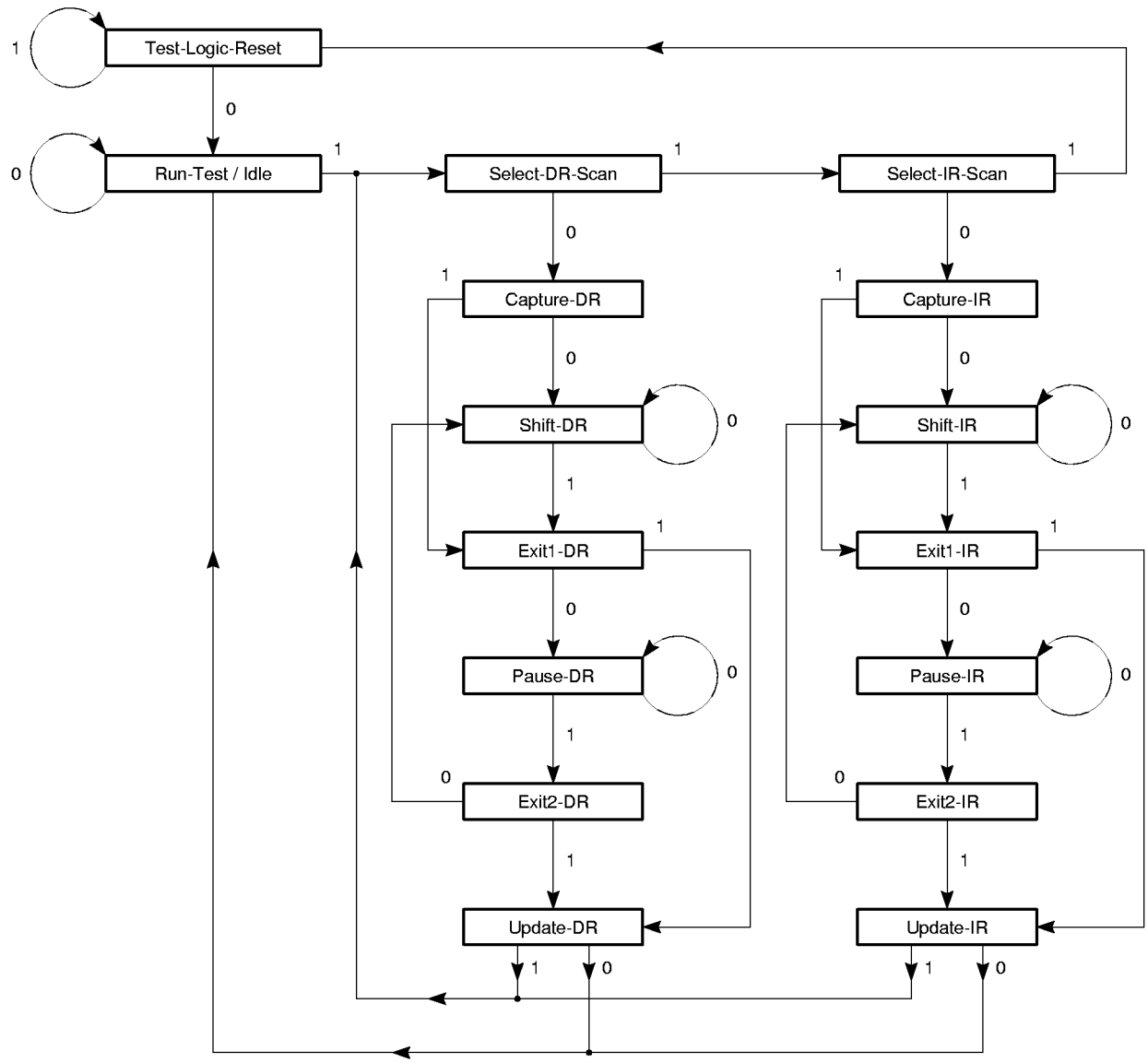
[μPD464318L (256K words by 18 bits)]

Bit no.	Signal name	Bump ID	Bit no.	Signal name	Bump ID
1	M2	5R	26	SA17	3B
2	SA5	6T	27	NC	2B
3	SA0	4P	28	SA9	3A
			29	SA10	3C
4	SA4	6R	30	SA13	2C
5	SA8	5T	31	SA12	2A
6	NC	7T			
			32	DQb1	1D
7	DQa1	7P	33	DQb2	2E
8	DQa2	6N			
			34	DQb3	2G
9	DQa3	6L			
			35	DQb4	1H
10	DQa4	7K	36	/SBb	3G
11	/SBa	5L	37	ZQ	4D
12	/K	4L	38	/SS	4E
13	K	4K	39	NC	4G
14	/G	4F	40	NC	4H
			41	/SW	4M
15	DQa5	6H			
16	DQa6	7G	42	DQb5	2K
			43	DQb6	1L
17	DQa7	6F			
18	DQa8	7E	44	DQb7	2M
			45	DQb8	1N
19	DQa9	6D			
20	SA2	6A	46	DQb9	2P
21	SA3	6C	47	SA11	3T
22	SA7	5C	48	SA14	2R
23	SA6	5A	49	SA1	4N
24	NC	6B	50	SA15	2T
25	SA16	5B	51	M1	3R

[μPD464336L (128K words by 36 bits)]

Bit no.	Signal name	Bump ID	Bit no.	Signal name	Bump ID
1	M2	5R	36	SA16	3B
			37	NC	2B
2	SA0	4P	38	SA9	3A
3	SA8	4T	39	SA10	3C
4	SA4	6R	40	SA13	2C
5	SA7	5T	41	SA12	2A
6	NC	7T	42	DQc9	2D
7	DQa9	6P	43	DQc8	1D
8	DQa8	7P	44	DQc7	2E
9	DQa7	6N	45	DQc6	1E
10	DQa6	7N	46	DQc5	2F
11	DQa5	6M	47	DQc4	2G
12	DQa4	6L	48	DQc3	1G
13	DQa3	7L	49	DQc2	2H
14	DQa2	6K	50	DQc1	1H
15	DQa1	7K	51	/SBc	3G
16	/SBa	5L	52	ZQ	4D
17	/K	4L	53	/SS	4E
18	K	4K	54	/C	4G
19	/G	4F	55	C	4H
20	/SBb	5G	56	/SW	4M
21	DQb1	7H	57	/SBd	3L
22	DQb2	6H	58	DQd1	1K
23	DQb3	7G	59	DQd2	2K
24	DQb4	6G	60	DQd3	1L
25	DQb5	6F	61	DQd4	2L
26	DQb6	7E	62	DQd5	2M
27	DQb7	6E	63	DQd6	1N
28	DQb8	7D	64	DQd7	2N
29	DQb9	6D	65	DQd8	1P
30	SA2	6A	66	DQd9	2P
31	SA3	6C	67	SA11	3T
32	SA6	5C	68	SA14	2R
33	SA5	5A	69	SA1	4N
34	NC	6B			
35	SA15	5B	70	M1	3R

TAP Controller State Diagram



Disabling The Test Access Port

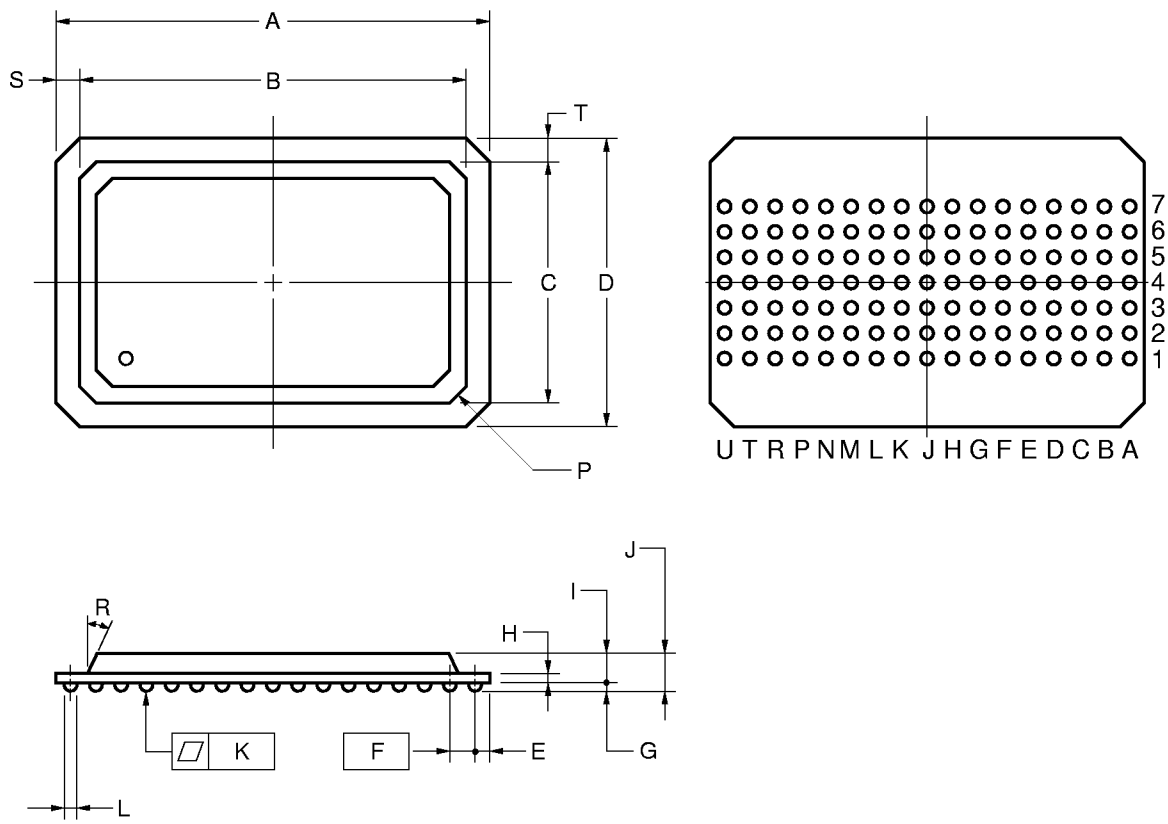
It is possible to use this device without utilizing the TAP. To disable the TAP Controller without interfering with normal operation of the device, TCK must be tied to V_{SS} to preclude mid level inputs.

TDI and TMS are designed so an undriven input will produce a response identical to the application of a logic 1, and may be left unconnected. But they may also be tied to V_{DD} through a 1 k resistor.

TDO should be left unconnected.

Package Drawing

119 PIN PLASTIC BGA



ITEM	MILLIMETERS	INCHES
A	22.0±0.2	0.866±0.008
B	19.5	0.768
C	12.0	0.472
D	14.0±0.2	0.551±0.008
E	0.84	0.033
F	1.27 (T.P.)	0.05 (T.P.)
G	0.6±0.1	$0.024^{+0.004}_{-0.005}$
H	0.56	0.022
I	1.46±0.1	$0.057^{+0.005}_{-0.004}$
J	2.30 MAX.	0.091
K	0.15	0.006
L	ϕ0.78±0.1	$\phi 0.031^{+0.004}_{-0.005}$
P	C0.7	C0.028
R	25°	25°
S	1.25	0.049
T	1.0	0.039

P119S1-R4

Recommended Soldering Conditions

Please consult with our sales offices for soldering conditions of the μPD464318L and μPD464336L.

Type of Surface Mount Device

μPD464318LS1: 119-pin plastic BGA
μPD464336LS1: 119-pin plastic BGA

[MEMO]

NOTES FOR CMOS DEVICES

① PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note: Strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

② HANDLING OF UNUSED INPUT PINS FOR CMOS

Note: No connection for CMOS device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. CMOS device behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF MOS DEVICES

Note: Power-on does not necessarily define initial status of MOS device. Production process of MOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed imme-diately after power-on for devices having reset function.

[MEMO]